AB1120

Bluetooth 3.0 Single Chip for HID Applications

Preliminary Specification

VERSION 0.20 12-APR-2011



Airoha Technology Corp.

This document is commercially confidential and must NOT be disclosed to third parties without prior consent. The information provided herein is believed to be reliable. But production testing may not include testing of all parameters. AIROHA Technology Corp. reserves the right to change information at any time without notification. (https://www.airoha.com.tw TEL:+886-3-6128800 FAX:+886-3-6128833 sales@airoha.com.tw)



This document is commercially confidential and must **NOT** be disclosed to third parties without prior consent.

The information provided herein is believed to be reliable. But production testing may not include testing of all parameters. AIROHA Technology Corp. reserves the right to change information at any time without notification.



Revision History

Version	Change Summary	Date	Author
0.10	Created	10-Feb-11	KH Chen
0.20	Updated	12-APR-11	KH Chen





INDEX

1	FI	EATURES	6
2	D	ESCRIPTION	7
		RADIO TRANSCEIVER	
		Baseband Processor	
	2.3	Serial Communication Interface	8
		I/O Ports	
	2.5	Peripherals	9
3	Р	IN DEFINITION	10
4		IN DESCRIPTION	
		SUGGESTION TO PIO INPUT/OUTPUT USAGE	
5	R	ADIO TRANSCEIVER	13
	5.1	RF FRONT-END	13
		Receiver	
	5.3	Transmitter	14
		Synthesizer	
6	В	ASEBAND PROCESSING UNIT	15
	6.1	BLUETOOTH FRAME DATA PROCESSOR	15
	6.2	Modulator and Demodulator	16
	6.3	BLUETOOTH TIMING PROCESSING UNIT	16
7	M	ICU AND MEMORY	17
8	P	ERIPHERAL CONTROL AND SERIAL COMMUNICATION INTERFACES	18
	8.1	Serial Peripheral Interface	18
	G	General Waveform	19
	И	Vrite Operation	19
	R	Pead Operation	20



Resync	20
9 POWER MANAGEMENT / REGULATION	21
9.1 Power Regulation	
9.2 Power Management Unit (PMU)	21
9.3 LI-MODE BATTERY CHARGER	21
10 SOFTWARE STACK	22
10.1 Key Features of HID Device Stack	
10.2 DEVELOPMENT ENVIRONMENTS AND TOOLS	
10.2.1 Software Development Environments	23
10.2.2 Test and Configuration Tools	23
11 ELECTRICAL CHARACTERISTICS	
11.1 Absolute Maximum Ratings	24
11.2 ECOMMENDED OPERATING CONDITIONS	24
11.3 DIGITAL TERMINALS	25
11.4 PIO CURRENT SINK/SOURCE CAPABILITIES	25
11.5 Reference Clock	
11.6 Switching Regulator	
11.6.1 Buck Regulator	
11.6.2 BOOST REGULATOR	27
11.7 Li-Mode Charger	27
11.8 Typical Current Consumption	28
11.9 Radio Characteristics	29
11.9.1 Transmitter (Basic Data Rate)	29
11.9.2 Receiver (Basic Data Rate)	
11.9.3 Transmitter (Enhanced Data Rate)	31
11.9.4 Receiver (Enhanced Data Rate)	32
12 PACKAGE INFORMATION	33



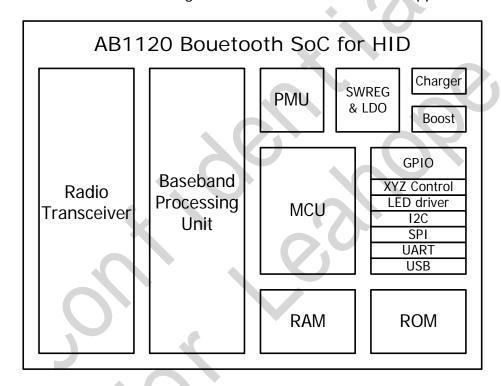
1 Features

- Compliant with Bluetooth 3.0 specifications
- HID profile version 1.0 compliant
- Supports AFH
- Supports sniff sub-rating for longer battery life & faster re-connect
- 18 Programmable GPIOs
- Supports 3 axis detection
- Supports SPI interface with 3/4-wire mode to sensor IC
- Supports I2C EEPROM interface
- Supports UART interface for firmware downloading and peripheral control
- Supports USB interface for host control
- Embedded 2 LED drivers with fader
- Low cost ROM based design with customer code support
- Embedded power management unit
- Integrated 1.8V Buck and 2.7~3.3V Boost switching regulator
- Embedded charger circuits with Li-battery mode
- Single RF port for transmitter and receiver
- Receiver sensitivity of –88dBm at basic data rate
- Transmit power up to +6dBm with 20 dB gain tuning range
- QFN 6mmx6mm 48 pin package



2 Description

AB1120 is a single-chip IC for HID applications, which supports Bluetooth system version 3.0 features including AFH function. It supports sniff sub-rating for longer battery life & faster re-connect. Bluetooth 3.0 simple-pairing mechanism is also implemented. AB1120's scatternet can join up to 3 piconets. It complies with RF transceiver, baseband processor, PMU, switching regulator, Boost regulator and Li-ion battery charger. Several Serial Communication Interfaces including USB, UART, I2C and SPI are supported.



2.1 Radio Transceiver

A common RF terminal is shared by the TX/RX paths of AB1120 with embedded TX/RX switch. Only an external balun and 3 matching components are required in the RF port.

A Low-IF architecture is implemented in the receiver part. The receiver sensitivity is –88dBm at basic data rate. The RSSI value which indicates the received signal power level is also measured and provided to the upper layers.



A direct-up conversion architecture is used in the transmitter part. The output power level at TX part is +6dBm for the basic data rate, with 20dB VGA gain tuning range.

A fractional-N synthesizer is implemented in AB1120 with internal loop filters such that no external components are required.

An internal crystal oscillator is integrated such that only an external 26MHz crystal is required. An internal 32.768KHz slow clock is also generated. External clock signal can also be fed into AB1120 instead of the 26MHz crystal clock signal.

2.2 Baseband Processor

The Baseband Processor of AB1120 supports Bluetooth 3.0 specifications including AFH. A digital data processing unit is in charge of the GFSK, DQPSK and D8PSK modulation / demodulation, channel filtering, error detection/correction, and burst framing.

A MCU-based Link Controller is implemented for the whole baseband control functions. A firmware is in charge of the Link Management Protocols, Profiles and MMI. Several hardware accelerators are implemented to support the baseband processing such as encryption, scatter-net operation, etc.

2.3 Serial Communication Interface

Several Serial Communication Interfaces including USB, UART and SPI are supported in AB1120. An I2C interface is implemented for EEPROM access.

2.4 I/O Ports

The total number of I/O pins of AB1120 is 18 pins, including 6 pins dedicated for input and 1 pin (PIO29) dedicated for EEPROM Write Protection. Other 11 I/O pins are programmable and support both input and output. A 3-axis detection is supported for external button control (i.e. PIO4/PIO5 are dedicated to ZA/ZB control in mouse application). Two LED drivers with faders for blue/red LEDs are also included.



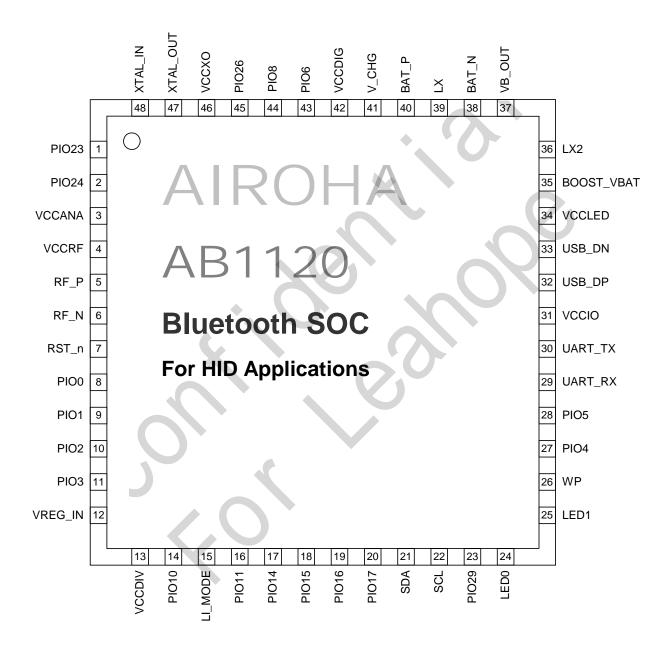
2.5 Peripherals

An on-chip switching regulator or a linear regulator is used to provide 1.8V VCC to the whole chip from battery supply. A 2.7~3.3V (selectable) Boost switching regulator is also included for the power supply of PMU, LED and external sensor IC of the HID device. A PMU is embedded in AB1120 for the power management affairs. A Li-ion battery charger circuits is also supported in AB1120.





3 Pin Definition





4 Pin Description

PIN	SIGANL	TYPE	DESCRIPTION	ALTERNATIVE
1	PIO23	Input/Output, Digital	Programmable IO	
2	PIO24	Input, Digital	Input Pin	
3	VCCANA	Supply, 1.8V	VCC for Analog	
4	VCCRF	Supply, 1.8V	VCC for RF	
5	RF_P	Input/Output, Differential RF	RF input/output P	
6	RF_N	Input/Output, Differential RF	RF input/output N	
7	RST_n	Input, Digital	Global reset	
8	PIO0	Input, Digital	Input Pin	
9	PIO1	Input, Digital	Input Pin	
10	PIO2	Input, Digital	Input Pin	
11	PIO3	Input, Digital	Input Pin	Motion Wake up
12	VREG_IN	Supply, 1.8V	VCO Regulator input	
13	VCCDIV	Supply, 1.8V	VCC for Divider	
14	PIO10	Input/Output, Digital	Programmable IO	
15	LI_MODE	Input, Digital	Battery mode indicator	
16	PIO11	Input/Output, Digital	Programmable IO	
17	PIO14	Input/Output, Digital	Programmable IO	SPI_CSB (NCS)
18	PIO15	Input/Output, Digital	Programmable IO	SPI_MOSI
19	PIO16	Input/Output, Digital	Programmable IO	SPI_MISO
20	PIO17	Input/Output, Digital	Programmable IO	SPI_CLK (SCLK)
21	SDA	Input/Output, Digital	I2C data line	
22	SCL	Input/Output, Digital	I2C clock line	
23	PIO29	Output, Digital	Output Pin (dedicated for EEPROM WP)	
24	LED0	Open Drain	LED 0 for Red Light	
25	LED1	Open Drain	LED 1 for Blue Light	
26	WP	Output, Digital	Write Protect Control for EEPROM	
27	PIO4	Input/Output, Digital	Programmable IO	ZB
28	PIO5	Input/Output, Digital	Programmable IO	ZA



29	UART_RX	Input, Digital	UART RX	
30	UART_TX	Output, Digital	UART TX	
31	VCCIO	Supply, 1.8V ~ 3.3V	VCC for IO ports	
32	USB_DP	Input/Output, Analog	USB Data I/O	
33	USB_DN	Input/Output, Analog	USB Data I/O	
34	VCCLED	Output	VCC Output, Supply to LED	
35	BOOST_VBAT	Input, Analog	Boost Enable Signal	
36	LX2	Supply	Boost Regulator input	
37	VB_OUT	Output, 2.7 ~ 3.3V	Boost Regulator output	
38	BAT_N	GND	Battery input N, Connected to GND	
39	LX	Analog	Switching Regulator output	
40	BAT_P	Supply	Battery input P, as Switching/Linear regulator input	
41	V_CHG	Supply	VCC for Li-ion Battery Charger	
42	VCCDIG	Supply, 1.8V	VCC for Digital circuits	
43	PIO6	Input/Output, Digital	Programmable IO	
44	PIO8	Input/Output, Digital	Programmable IO	
45	PIO26	Input, Digital	Input Pin	
46	VCCXO	Supply, 1.8V	VCC for XO	
47	XTAL_OUT	Analog	Crystal output	
48	XTAL_IN	Analog	Crystal input	

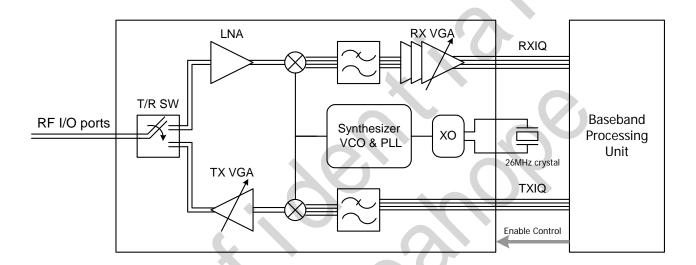
4.1 Suggestion to PIO Input/Output Usage

PIO	Suggestion
0, 1, 2, 3, 24, 26	Used as INPUT pins only
	Could be used as INPUT or OUTPUT.
4, 5, 6, 8, 10, 11,	Note:
14, 15, 16, 17, 23	PIO4, PIO5 are dedicated for ZA/ZB usage of mouse application
	PIO14, PIO15, PIO16, PIO17 are also used as SPI interface
29	OUPUT, PIO29 is dedicated to EEPROM Write Protection



5 Radio Transceiver

The AB1120 RF transceiver is a 2.4GHz-band transceiver for the Bluetooth applications. There are three main functions – transmitter, receiver, and synthesizer. The enable control signals of these functions are given by the Baseband Processing Unit.



5.1 RF Front-end

The RX input ports and TX output ports share the same RF terminals such that no external T/R switch is required. Only a balun and some matching components are placed outside the RF terminals.

5.2 Receiver

The AB1120 RF receiver implements a Low-IF architecture, which is composed with two parts: RF front-end and Low-IF part. The RF front-end part comprises a LNA and a quadrature mixer. The LIF part comprises a low-pass filter (LPF) for out-band filtering and a variable gain amplifier (VGA).



The LNA input shares the same RF ports with TX output. The RX front-end gain could be adjusted, and thus reduce the probability of bit errors caused by poor signal-to-noise ratio. After the LNA is followed by a quadrature mixer that down-converts the RF signal to Low-IF band.

At the LIF part, the down-converted signal is first low-pass filtered by the LPF, amplified by the VGA, and then sent to the ADC for demodulation. The 3dB bandwidth of the LPF could be adjusted through RF registers. The LNA and VGA provide more than 80dB gain control range.

5.3 Transmitter

The AB1120 RF transmitter implements a direct-up-conversion architecture, which comprises a LPF, a modulator and a VGA stage. The TX baseband signals are fed from baseband DAC, generated by the baseband modulators. A LPF is implemented to attenuate the second sidelobe of signal spectrum and unwanted oversampling clock or spurious signals. The 3dB bandwidth of the LPF could be adjusted through RF registers. The VGA provides variable gain with more than 28dB dynamic range, and could be controlled through RF register interface.

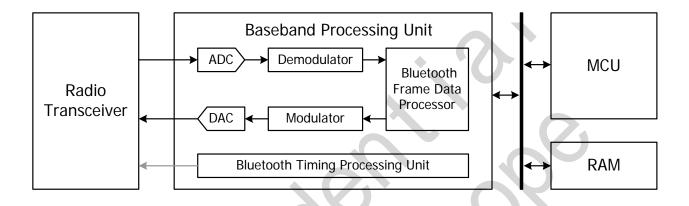
5.4 Synthesizer

The AB1120 implements a fractional-N synthesizer with embedded VCO and loop filter without the need of external components. AB1120 also integrates an internal crystal oscillator that only an external 26MHz crystal is required. External clock signal can also be fed into AB1120 instead of the 26MHz crystal clock signal.



6 Baseband Processing Unit

The Baseband Processing Unit (BPU) comprises a Digital-to-Analog Convert (DAC), an Analog-to-Digital Converter (ADC), a digital modulator, a digital demodulator, a Bluetooth Frame Data Processor, and a Timing Processing Unit (TPU).



6.1 Bluetooth Frame Data Processor

AB1120 baseband processing unit supports all packet types of Bluetooth 1Mbps, 2Mbps and 3Mbps modes. On transmitter side, the frame data processor can construct Bluetooth data packet according to the packet type given by MCU. The constructed data packet then will be converted to analog modulated signal format by the modulator and DAC.

On the receiver side, the analog received signal will be first converted to digitized data format by the ADC and demodulator, and then the frame data processor will de-construct the received data to several parts and identify if the received signal is a valid Bluetooth packet and if the packet is for the device itself. The received header data and PSDU data will be stored into memory if it is a valid Bluetooth data packet and is for the device itself.

Access code check, Header Error Check (HEC) and PSDU CRC checking functions are performed by the frame data processor, too, to see if this received signal is valid and error free or not. A data whitening circuit and an encryption engine are also included in the frame data processor for both transmitter and receiver paths.



6.2 Modulator and Demodulator

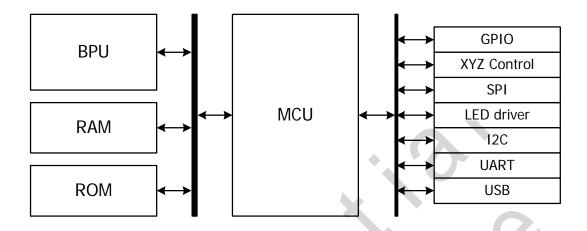
The modulator can generate GFSK, DQPSK and D8PSK signals according to which data rate is adopted in the frame data. The demodulator can convert the received data signal to digitized data bit format according to the modulation type indicated in the header region.

6.3 Bluetooth Timing Processing Unit

A Bluetooth Timing Processing Unit (TPU) is embedded in the Baseband processing unit. TPU is in charge of generating RF timing control signals to the RF radio part, such as TX enabling signals and RX enabling signals.



7 MCU and memory



The micro-control unit (MCU) executes the Bluetooth protocol software stack, controls the Bluetooth baseband processing unit (BPU) and Serial Communication Interfaces. 2Mbits ROM is embedded in AB1120 to store the software stack, and 24Kbytes RAM is provided to support the MCU and baseband data processing.

Data are transferred between MCU, ROM, RAM and BPU with a shared memory bus. Another peripheral bus is connected with MCU for the peripherals access.



8 Peripheral Control and Serial

Communication Interfaces

The total number of I/O pins of AB1120 is 18, including 6 pins dedicated for input, 1 pin for EEPROM Write Protection(PIO29). Other 11 I/O pins are programmable and support both input and output directions. The ROM firmware provides a possibility that developers could select different PIOs for input without re-compile their customer code. An easy-to-use configuration utility program can modify the PIO selections and up to 16 pins could be programmed as input simultaneously, for example a device with 16 buttons, and thus can fulfill the HID MMI requirements in most applications.

There are one set of 3-axis detection IO ports, 2 LED drivers, one SPI interface, and one I2C interface connected to MCU with a peripheral bus. An UART and an USB for firmware downloading and peripheral control are also supported.

The LED drivers integrate fader function and can drive red and blue LEDs for HID device indication purposes.

The I2C interface is used to connect to a serial EEPROM, which supports 100KHz / 400KHz / 800KHz bus clock rate at 1.8 or 3.3V voltage supply.

The UART interface supports up to 3M baud rate. The USB interface supports USB 2.0 full speed. Both of them are connected to the peripheral interface.

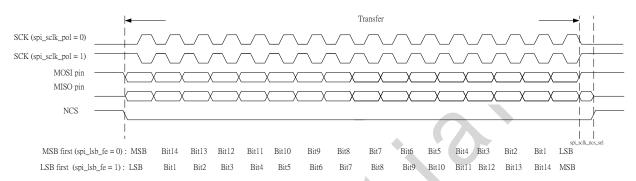
8.1 Serial Peripheral Interface

A SPI interface allows AB1120 to communicate with external HID device controller to exchange the MMI information such as button, axis control, etc. Both 3-wire and 4-wire mode SPI interfaces are supported in AB1120. When 3-wire mode is selected, pin 18 (SPI_MOSI) would be data I/O pin of the SPI interface. Only Master Mode is supported in AB1120.

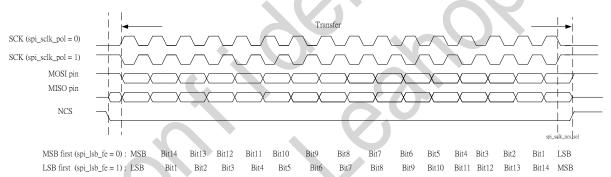


General Waveform

$spi_sclk_pha = 0$



$spi_sclk_pha = 1$

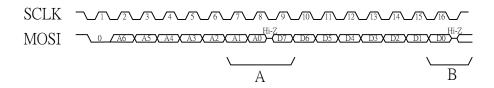


Write Operation

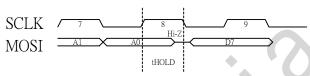




Read Operation

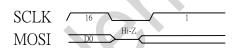


Part A:

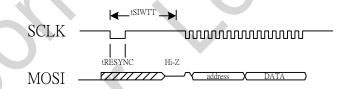


tHOLD: MOSI Read Hold Time

Part B:



Resync



tSIWTT: Serial Interface Watchdog Timer Timeout

tRESYNC : Serial Interface RESYNC



9 Power Management / Regulation

AB1120 integrates a Power Management Unit (PMU), two internal switching regulators: one Bulk regulator from VBAT to 1.8V VCC, and one Boost regulator from VBAT to higher voltage (2.7~3.3V, selectable), and a 1.5V LDO regulator for VCO. A Li-ion battery charger is also embedded.

9.1 Power Regulation

A switching regulator is embedded to convert VBAT to 1.8V voltage supply for the core of AB1120. There is another Boost regulator to up convert the VBAT supply voltage to a higher level (2.7~3.3V, selectable) for the power supply of PMU, LED driver, and external sensor IC. All these regulators are integrated within AB1120.

9.2 Power Management Unit (PMU)

A PMU is designed in AB1120 for the power management affairs. During general operations, MCU may get into sleep mode for power saving. At this moment the PMU watches the keys and wake up MCU if one of the keys is pressed. PMU also monitors the battery voltage and reports to MCU.

9.3 Li-mode Battery Charger

The Li-mode battery charger of AB1120 provides several operation modes including Trickle mode, Constant Current mode (CC mode), Constant Voltage mode (CV mode), and Standby mode. When an external power supply is connected to AB1120, PMU will first detect if the voltage is correct and enable the charger circuit. When Charger circuit is enabled, it will detect the battery voltage and enters the associated mode to charge the battery, i.e. Trickle, CC or CV mode. When the battery voltage reaches a high threshold, the charger will enter standby mode and keep watching the battery voltage. If the battery voltage drops to a lower threshold, charger circuit will re-charge the battery again.



10 Software Stack

10.1 Key Features of HID Device Stack

The Airoha AB1120 HID software stack provides total solution of Bluetooth HID profile (device role), including all protocol stacks and profiles defined in HID v1.0. In additional, it has some extra features as shown below:

- Configurable MMI: Customers can modify user interface behavior by setting registers in EEPROM. In additional, AB1120 provides a set of function interface in ARIOHA HID Customer Code Environment. Customers can re-write these functions to configure their own MMI.
- Support mainstream optical/laser sensors by default, and can be chosen by EEPROM settings. Customers can re-write the MMI using ARIOHA HID Customer Code Environment for other sensor.
- Good report rate for HID Mouse. (up to 125Hz)
- Low-power operation based on various hardware-wakeup mechanisms.

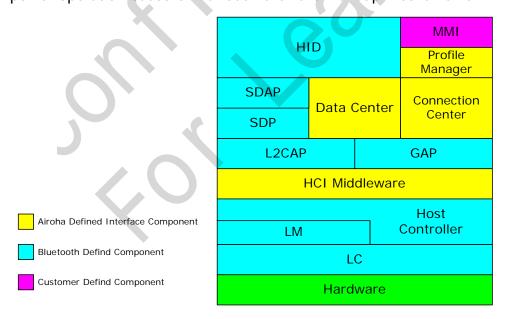


Figure 10.1: HID Software Stack



10.2 Development Environments and Tools

10.2.1 Software Development Environments

AB1120 provides a set of function interface in **ARIOHA HID Customer Code Environment**. Customers can rewrite these functions to control their hardware components, such as keypad, LED, SPI, optical sensor and etc..

10.2.2 Test and Configuration Tools

Various tools are provided for testing and configuration as shown below:

AB1120 LabTest

AB1120 LabTest provides the capability for RF testing and can be used as HID module testing during mass-production.

AB1120 HID Configuration tool

AB1120 HID Configuration tool provides to customers the capability to configure the various settings, such as Button I/O, LED behavior, Battery Parameters, and Sensor settings stored in EEPROM.



11 Electrical Characteristics

11.1 Absolute Maximum Ratings

AB1120 could be damaged by any stress in excess of the absolute maximum ratings listed below.

ITEM	MIN.	MAX.
I/O supply voltage (VCCIO)	-0.3V	5.5V
Boost supply voltage (VB_IN)	-0.3V	5.5V
Charger supply voltage (V_CHG)	-0.3V	6.5V
Switching Regulator supply voltage (BAT_P)	-0.3V	5.5V
Operating temperature	-40°C	+85°C
Storage temperature	-65°C	+150°C
LNA input level		+10 dBm
PA output load mismatch	-	10:1

11.2 Recommended Operating Conditions

Item	Min.	Тур.	Max.	Unit
Core supply voltage (VCCANA, VCCRF, VCCDIV, VREG_IN,		1.0		V
VCCDIG, VCCXO)		1.8		V
I/O supply voltage (VCCIO)	1.8		3.6	V
Boost supply voltage (VB_IN)	1.6		3.3	V
Charger supply voltage (V_CHG)	4.5	5	6.5	V
Switching Regulator supply voltage (BAT_P)	2		4.2	V



11.3 Digital Terminals

Item	Min.	Тур.	Max.	Unit
Input Voltage Levels				
Input logic level low (V _{IL})	0		0.3*VCCIO	V
Input logic level high (V _{IH})	0.7*VCCIO		VCCIO+0.4	V
Output Voltage Levels (1.7V≦VCCIO≦1.9V)				
Output logic level low (V_{OL}), I_{O} =4.0mA			0.4	V
Output logic level high (V _{OH}), I _O =-4.0mA	VCCIO-0.4			V
Output Voltage Levels (2.7V ≤ VCCIO ≤ 3.0V)				
Output logic level low (V_{OL}), I_{O} =4.0mA			0.2	V
Output logic level high (V _{OH}), I _O =-4.0mA	VCC10-0.2			V

11.4 PIO Current Sink/Source Capabilities

Item	Output	Criteria	Capability	Note			
	VCCIO = 3.3 V						
Max. Input Current	Low	$Vout \leq 0.3 \times VCCIO$	>10 mA				
Max. Output Current	High	Vout≧ 0.7×VCCIO	>10 mA				
		VCCIO = 2.7 V					
Max. Input Current	Low	$Vout \leq 0.3 \times VCCIO$	>10 mA				
Max. Output Current	High	Vout≧ 0.7×VCCIO	>10 mA				
This table is applied	to PIO # 4, 5,	6, 8, 10, 11, 14, 15, 16,	17, 23				



11.5 Reference Clock

Item	Min.	Тур.	Max.	Unit
Crystal Requirement				
Nominal Frequency		26		MHz
Operating Temperature Range	-30	25	85	$^{\circ}\!\mathbb{C}$
Frequency Stability over Operating Temperature Range	-10		+10	ppm
Crystal Oscillator Characteristics				
Tunning Range (with 128 steps)		95		ppm
Negative resistance (@ C0 = 0.89pF, CL = 10pF)	.	140		Ω
External Reference Clock Requirement				
Input Frequency	K	26		MHz
Clock Input Level (AC-coupled, sinusoidal or square wave)	0.2		1.8	V pk-pk
XTAL_IN input impedance		10		ΚΩ
XTAL_IN input capacitance		10	7	pF

11.6 Switching Regulator

11.6.1 Buck Regulator

external inductor = 33uH, external capacitor = 4.7uF

It	em	Min.	Тур.	Max.	Unit
Input Voltage		2		3.6	V
Output Voltage	BAT_P > 2.2V	1.7	1.8	1.9	V
Rated Output Current (Iout)	BAT_P > 3.6V			60	mA
Switching Frequency			1		MHz
Power Efficiency	@lout max		80		%



11.6.2 Boost Regulator

external inductor = 4.7uH, external capacitor = 10uF

Item		Min.	Тур.	Max.	Unit
Input Voltage		1.6		3.6	V
Output Voltage at VB_OUT = 3	3V setting	2.7	3	3.3	V
Rated Output Current (Iout)	VB_IN = 2.4V, VB_OUT=3V			100	mA
Switching Frequency			566		KHz
Power Efficiency	@Iout max		80		%

11.7 Li-Mode Charger

Item	Min.	Typ.	Max.	Unit
Input Voltage	4.5	5	6.5	٧
Charge Current (CC Mode)	40		100	mA
Trickle Charge Current	5	5.5	6	mA
Trickle Charge Threshold Voltage		2.8		٧
Regulated Output (Float) Voltage	4.16	4.2	4.24	٧
Battery charger termination current		10		%
Recharge Battery Hysteresis Voltage		100		mV



11.8 Typical Current Consumption

Core Supply Voltage = 1.8V @ 25℃

Item	Min.	Тур.	Max.	Unit
Transmit (Peak Current)		53		mA
Receive (Peak Current)		48		mA
DM1(TX mode)		53		mA
DM1(RX mode)		48		mA
Sniff mode, 10ms		5.1		mA
Sniff mode, 100ms				mA
Sniff mode, 1.28s		*	O .	mA
Deep sleep (disconnected, link loss state, wake on interrupt)		27		μ A

The current consumption was measured directly on the buck and boost output.



11.9 Radio Characteristics

11.9.1 Transmitter (Basic Data Rate)

Item			Тур.	Max.	Unit
Maximum RF transmit Power*1			1		dBm
RF power control range			20		dB
20dB bandwidth for modulate	ed carrier	\limits	950		KHz
	+2MHz		-21		dBm
Adjacent channel transmit	-2MHz				dBm
power	+3MHz		-47		dBm
	-3MHz		-43		dBm
Francisco deviation	Average deviation in payload		140)	KHz
Frequency deviation	Maximum deviation in payload		160	\	KHz
Initial carrier frequency tolera	ance	V	10		KHz
	DH1 packet		15		KHz
Drift	DH3 packet		15		KHz
	DH5 packet		15		KHz
Drift Rate			5		KHz/50us
2 nd Harmonic Content				-30	dBm
3 rd Harmonic Content				-30	dBm

^{*1} The maximum RF transmit power could reach to 6dBm with appropriate settings



11.9.2 Receiver (Basic Data Rate)

Ite	em	Min.	Тур.	Max.	Unit
	2.402GHz		-88		dBm
Sensitivity at 0.1% BER	2.441GHz		-88		dBm
	2.480GHz		-88		dBm
Maximum input power at 0.1%	BER	0			dBm
Co-Channel interference			7		dB
	$F = F_0 + 1MHz$		-5		dB
	$F = F_0 - 1MHz$		-5		dB
Adjacent channel selectivity	$F = F_0 + 2MHz$		-35		dB
C/I	$F = F_0 - 2MHz$		-28		dB
	$F = F_0 + 3MHz$		-43		dB
	$F = F_{image}$		-18		dB
Maximum level of intermodulat	tion interference	10	-32		dBm
	30-2000 MHz		-3		dBm
Blocking @Pin=-67dBm with	2000-2400 MHz		-10		dBm
0.1%BER	2500-3000 MHz		-10		dBm
	3000-12750 MHZ		0		dBm



11.9.3 Transmitter (Enhanced Data Rate)

Item	Min.	Тур.	Max.	Unit	
Relative transmit power			-3		dB
π /4 DQPSK max carrier frequency stability $ \omega_{ m o} $			1		KHz
π /4 DQPSK max carrier frequency	stability ω_i		3		KHz
π /4 DQPSK max carrier frequency	stability ω _o +ω _i		4		KHz
8DPSK max carrier frequency stabili	ity ω ₀		1		KHz
8DPSK max carrier frequency stabili	ity ω _i	*	3		KHz
8DPSK max carrier frequency stabili	ity ω ₀ +ω _i		4		KHz
	RMS DEVM		7		%
π /4 DQPSK Modulation Accuracy	99% DEVM				%
	ability \omega_i ability \omega_0 + \omega_i ability \omega_0 + \omega_i \omega_0 \omega_0 \omega_0 + \omega_i \omega_0 + \omega_0 + \omega_i \omega_0 + \omeg		19		%
	RMS DEVM		7	,	%
8DPSK Modulation Accuracy	99% DEVM				%
	\(\omega_0 \) \(\omega_		19		%
	F > F0 + 3MHz				dBm
	F < F0 - 3MHz				dBm
	F = F0 + 3MHz		-34		dBm
In hand anurious emissions	F = F0 - 3MHz		-40		dBm
In-band spurious emissions	F = F0 + 2MHz		-23		dBm
	F = F0 - 2MHz		-33		dBm
	F = F0 + 1MHz		-30		dBm
	F = F0 - 1MHz		-30		dBm
EDR Differential Phase Encoding			0		%



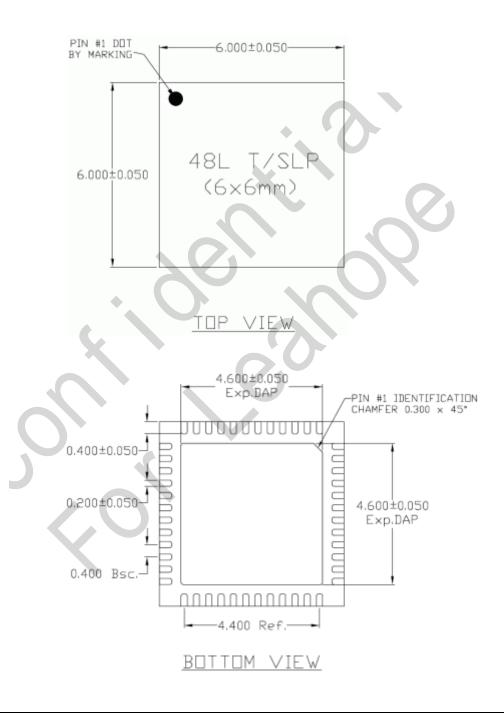
11.9.4 Receiver (Enhanced Data Rate)

Ite	em		Min.	Тур.	Max.	Unit
Concitivity at 0.010/ FDD	π /4 DQPSK			-89		dBm
Sensitivity at 0.01% EDR	8DPSK			-81		dBm
Maximum input power at 0.1%	τ /4 DQPSK			0		dBm
BER	8DPSK			0		dBm
Co-Channel interference	π /4 DQPSK			10		dB
Co-Channel interrerence	8DPSK			17		dB
	$F = F_0 + 1MHz$	π /4 DQPSK		-11		dB
	$\Gamma - \Gamma_0 + IMITZ$	8DPSK		-5		dB
	$F = F_0 - 1 MHz \begin{vmatrix} \pi / 4 \text{ DQPSK} & -11 \\ 8 DPSK & -5 \end{vmatrix}$	π /4 DQPSK		-11	V	dB
			dB			
	E E OMI	π /4 DQPSK		-34		dB
Adjacent channel selectivity	$F = F_0 + 2MHz$	8DPSK		-28		dB
C/I	$F = F_0 - 2MHz$	π /4 DQPSK		-30		dB
		8DPSK		-23		dB
	E - E + 2MHz	π /4 DQPSK		-41		dB
	$F = F_0 + 3MHz$	8DPSK		-34		dB
	E E	π /4 DQPSK		-15		dB
	$F = F_{image}$	8DPSK		-8		dB

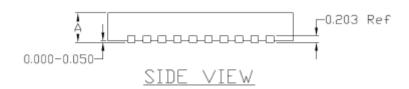


12 Package Information

SAW QFN 48LD, 6x6x0.85 PKG 0.40 PITCH POD







NOTE:

1) TSLP AND SLP SHARE THE SAME EXPOSE DUTLINE BUT WITH DIFFERENT THICKNESS:

		TSLP	SLP
	MAX.	0.800	0.900
Α	N□M.	0.750	0.850
	MIN.	0.700	0.800